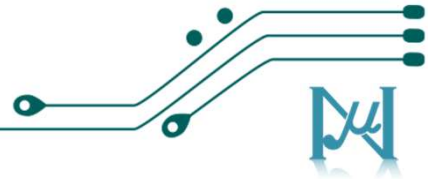


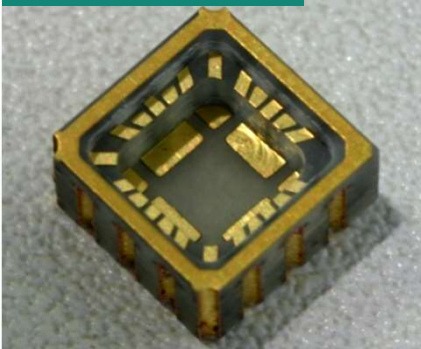
Cavity PCB



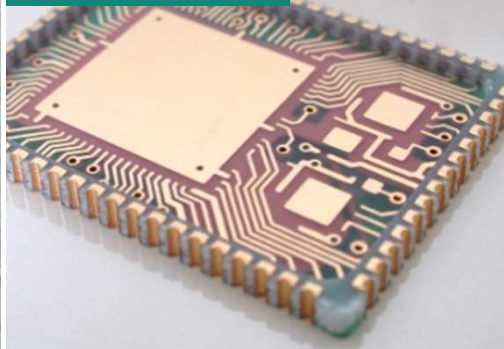
Combination of our technology

We provide various package printed circuit boards and module PCBs with cavity structure exposing selected inner layer patterns (bonding pads, ground layers, etc.) on multi layer PCB and build-up PCB.

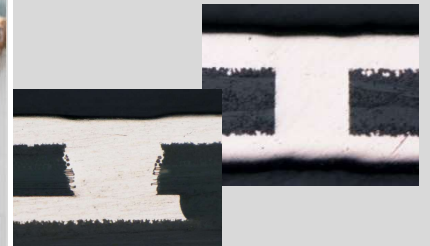
Two-tiered cavity



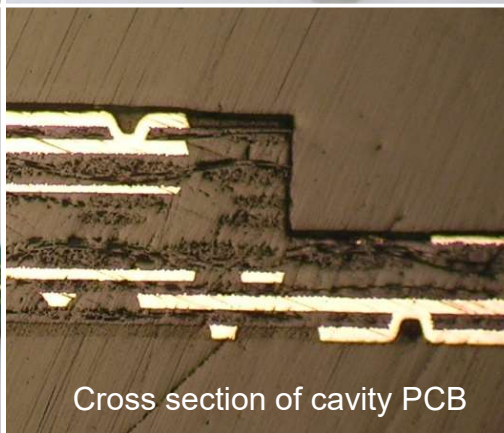
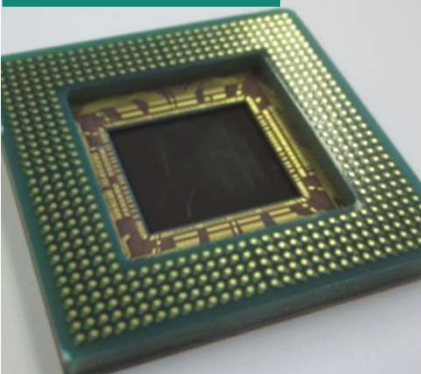
Side through hole



Through hole filling
Via filling

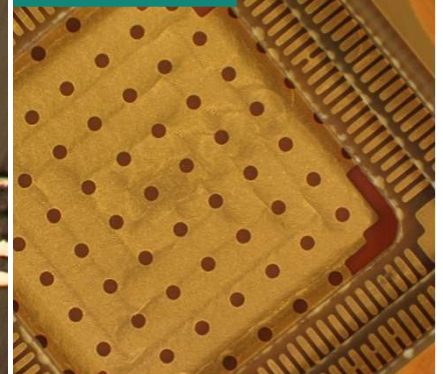


Metal lamination

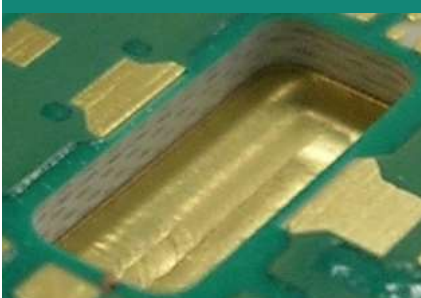


Cross section of cavity PCB

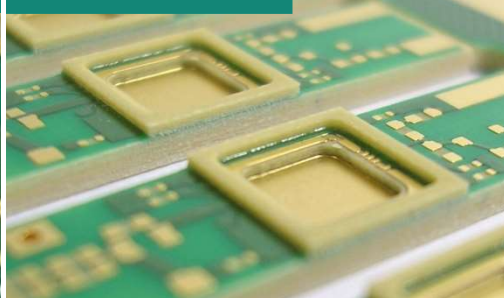
Thermal via



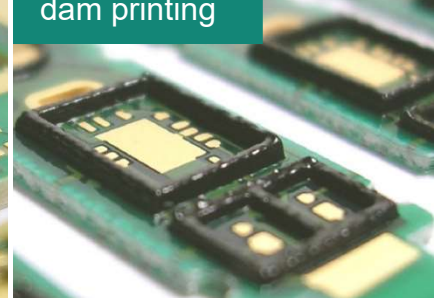
Copper layer exposing



Frame lamination



Thick solder
dam printing



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